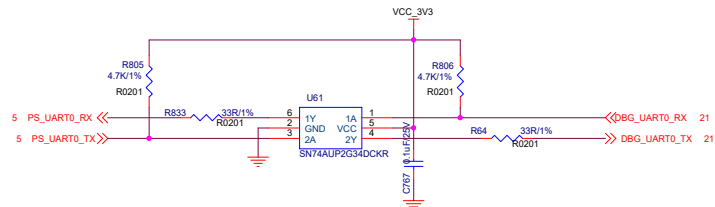
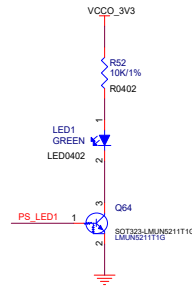
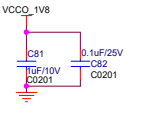
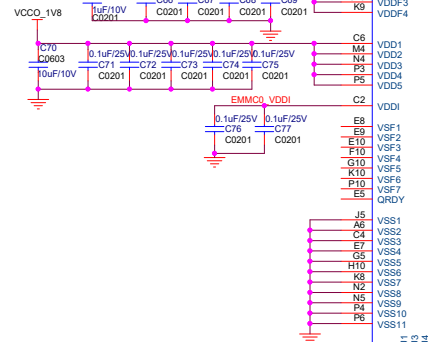
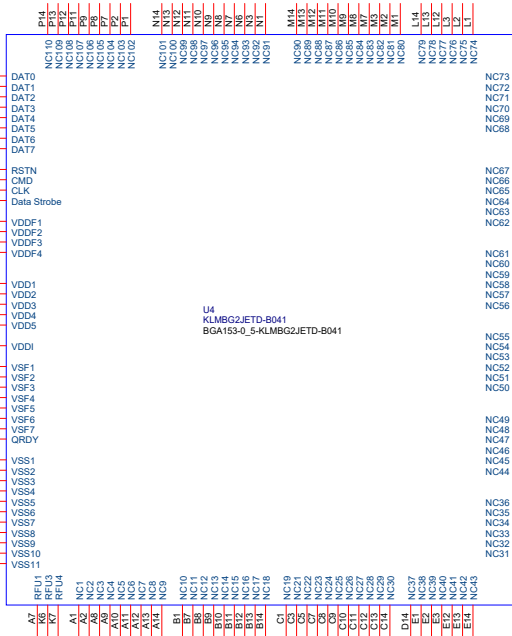
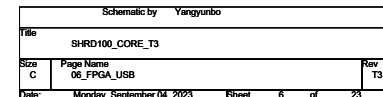
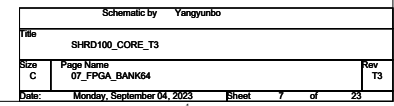
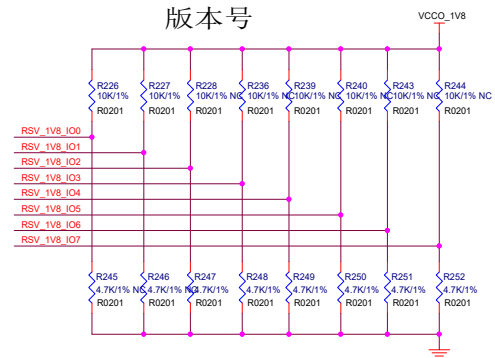
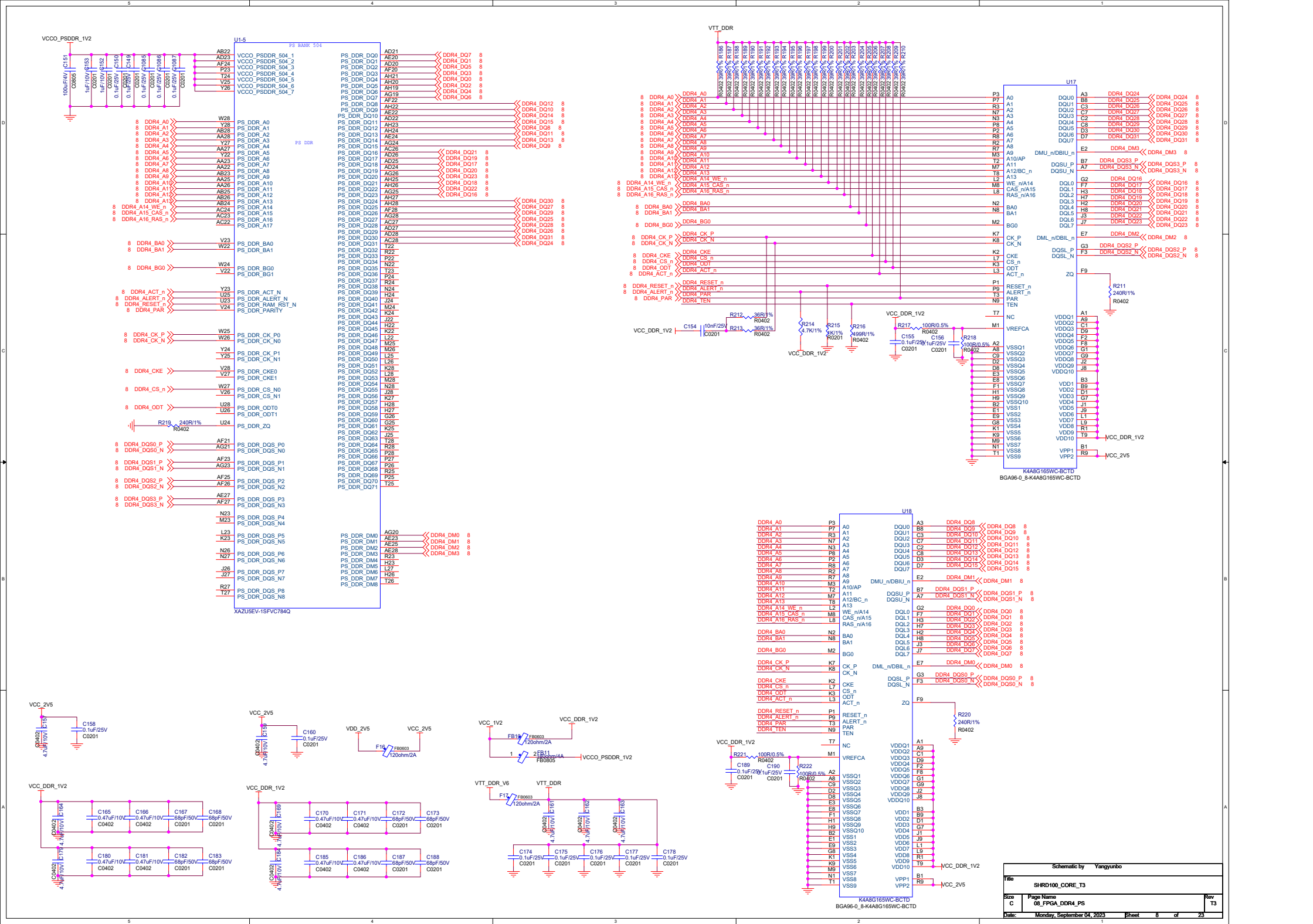


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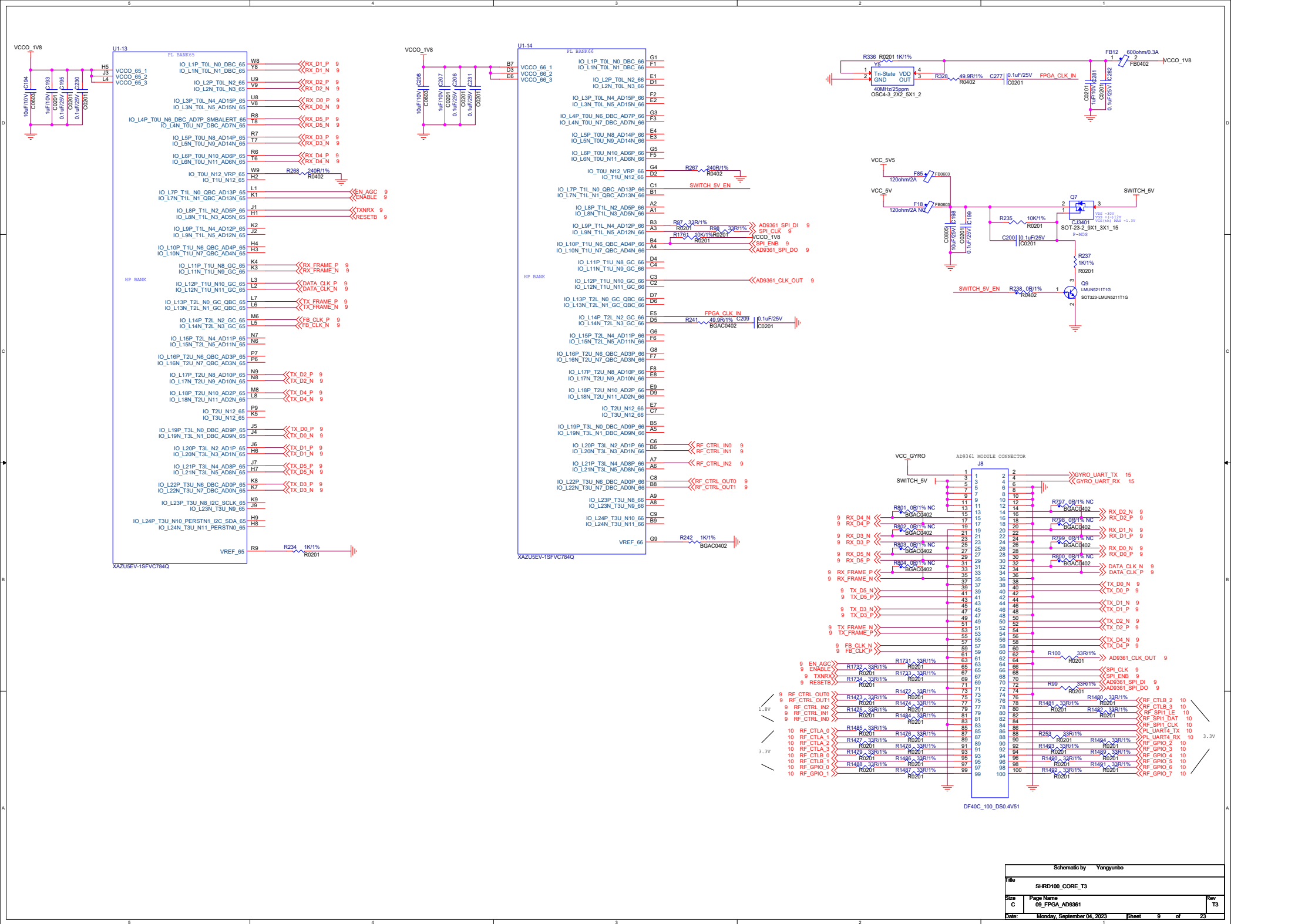


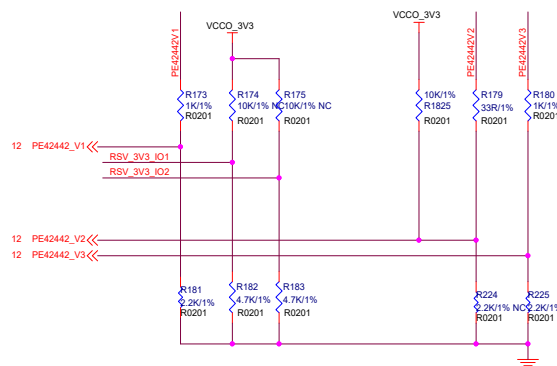
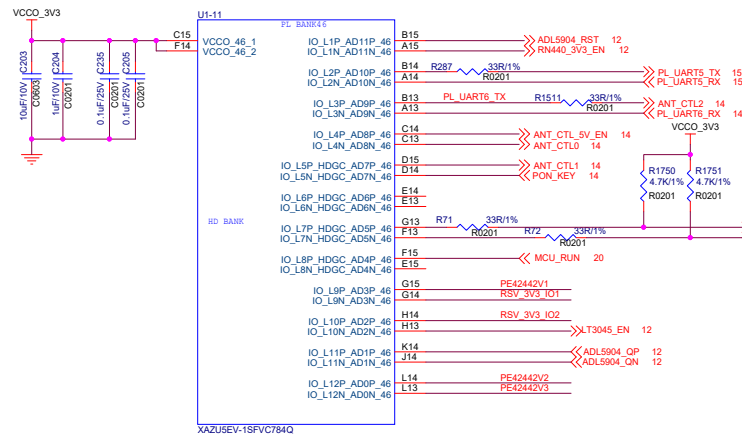
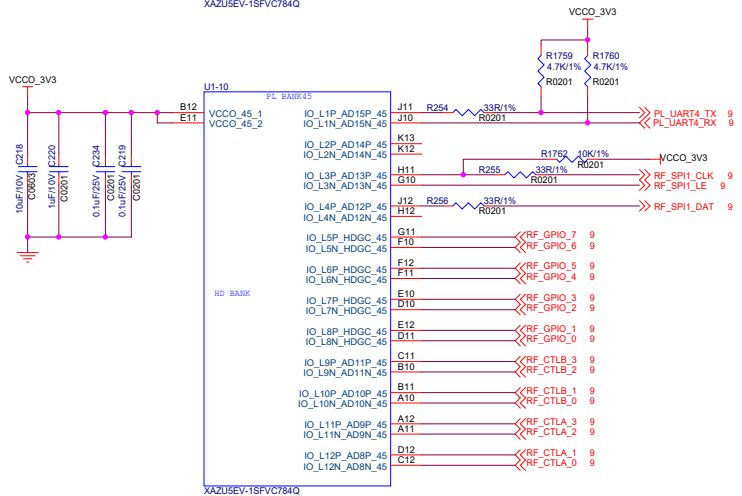
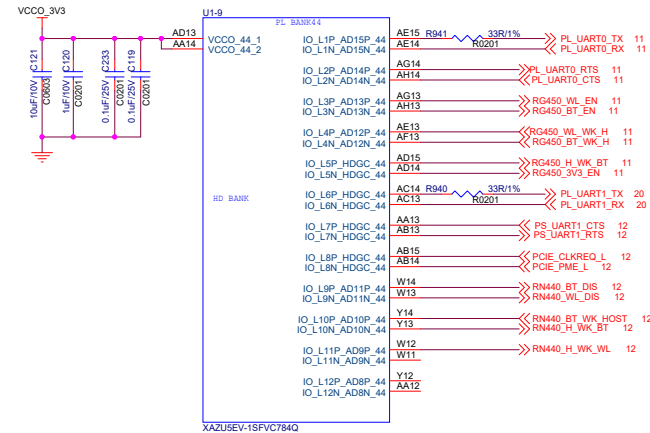
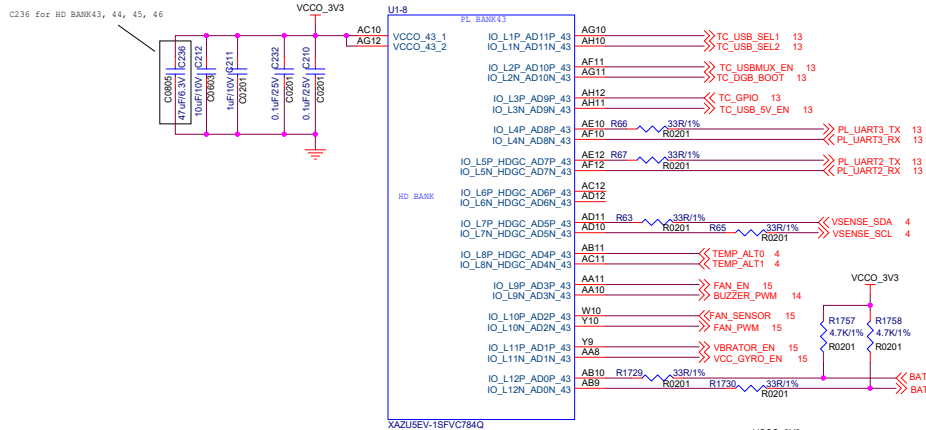


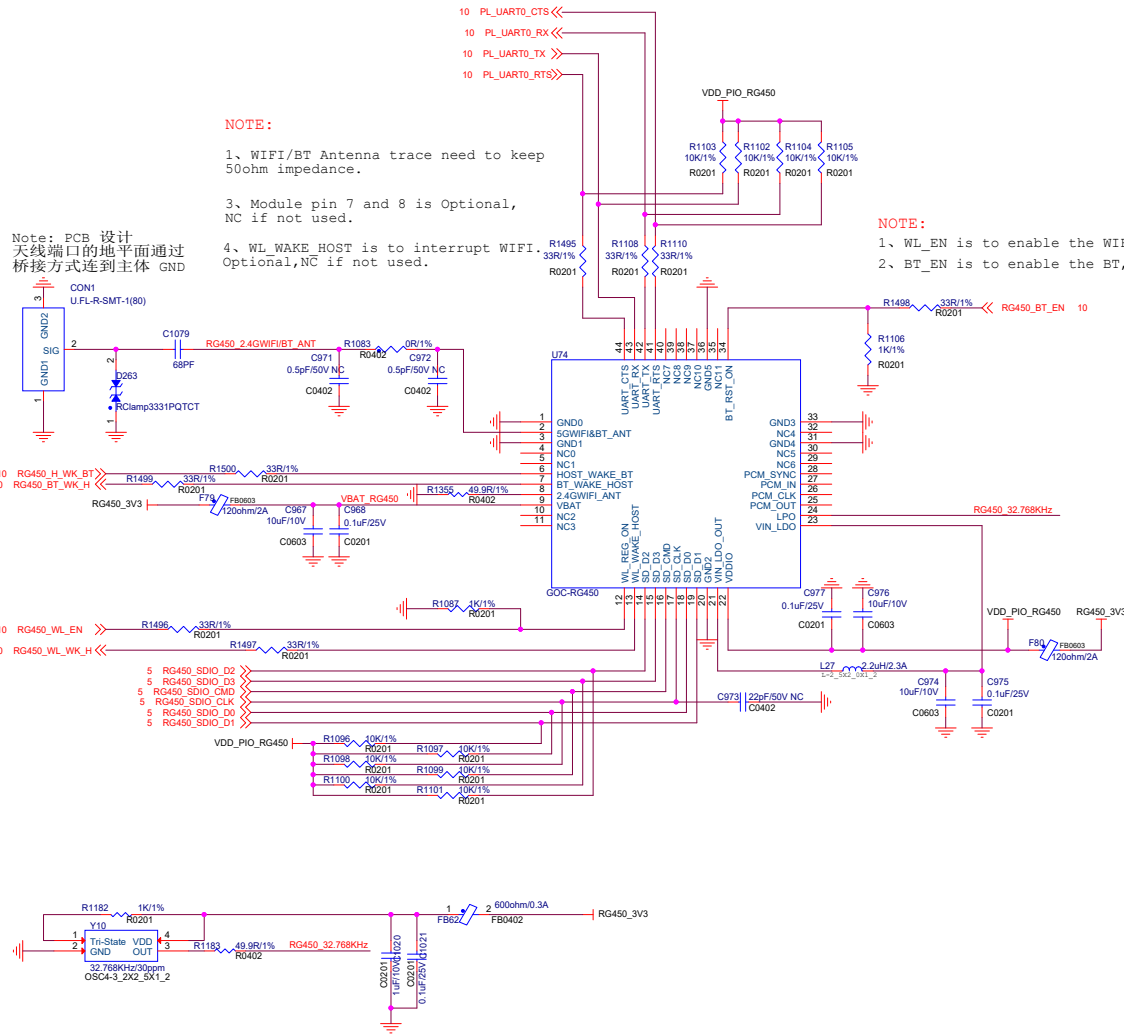




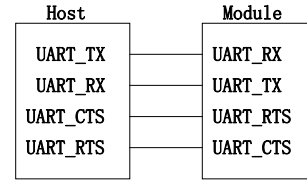




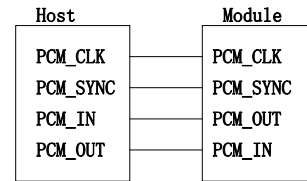




UART Connection between Module and Host.



PCM Connection between Module and Host.



**SDIO NOTE:**

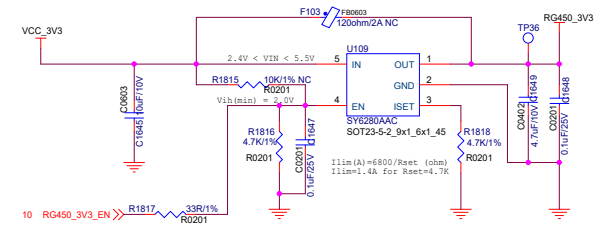
- 1、Trace total length < 4000mils, and six signals trace length difference < 300mils.
- 2、Add damping resistor.
- 3、SDIO signals do not allow crossed over and overlapped.
- 4、CLK signals should keep well ground.
- 5、The less changing the PCB layer the better.

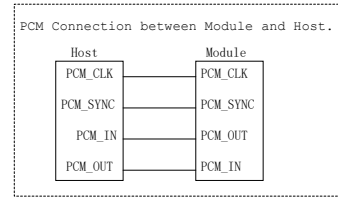
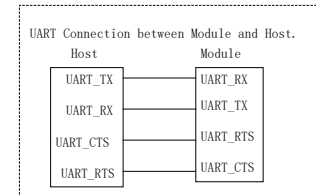
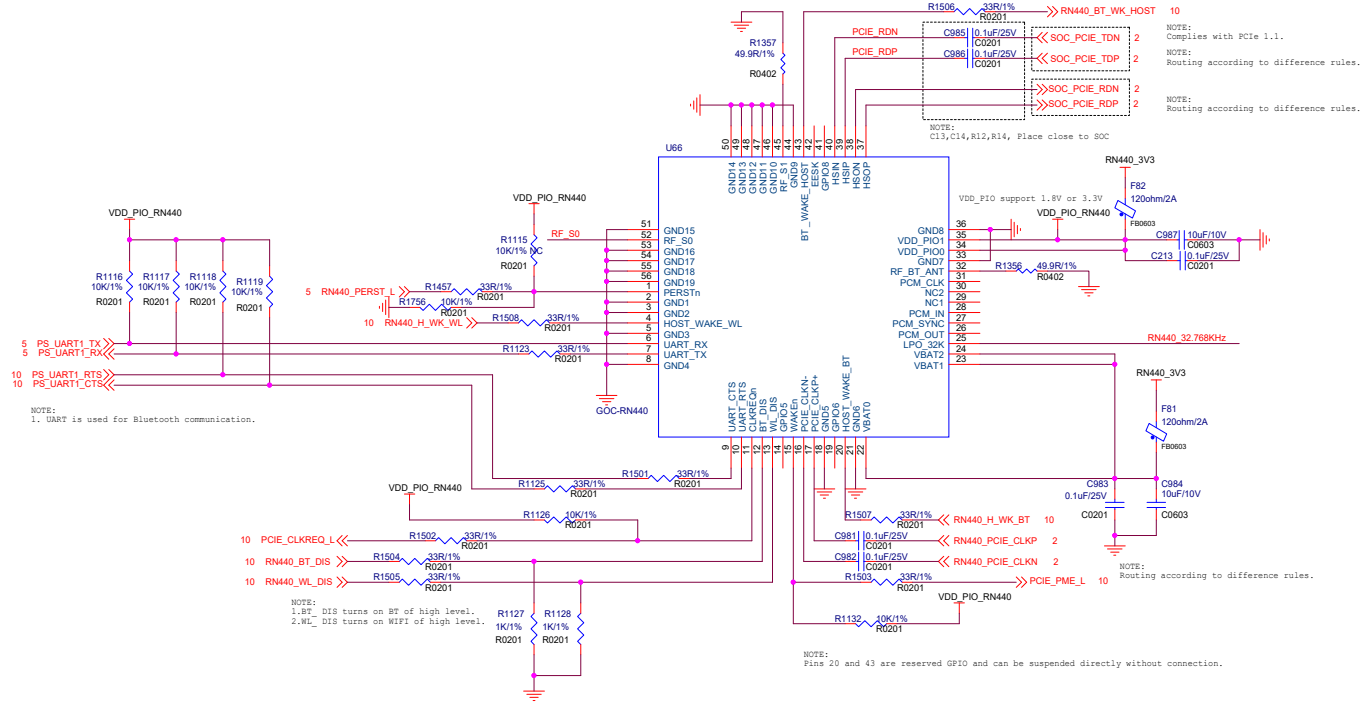
**Power and LPO Note:**

- 1.This module requires two sets of power supply VDD\_3.3V and VDD\_PIO. Independent power supply is recommended. The power ripple is less than 80 mV. Current for power supply :

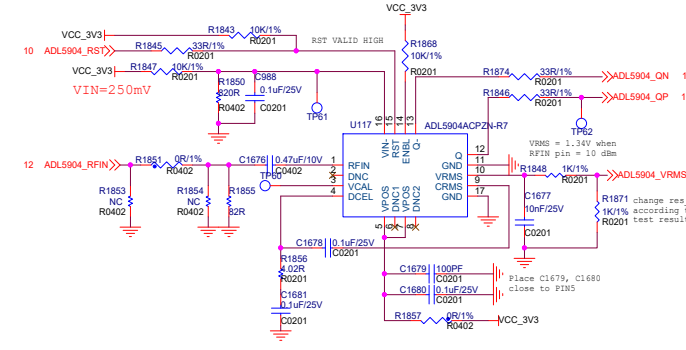
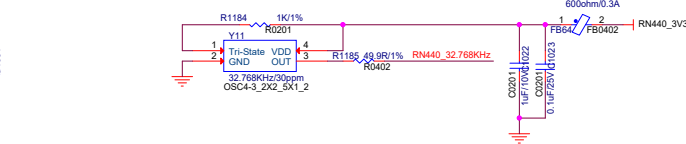
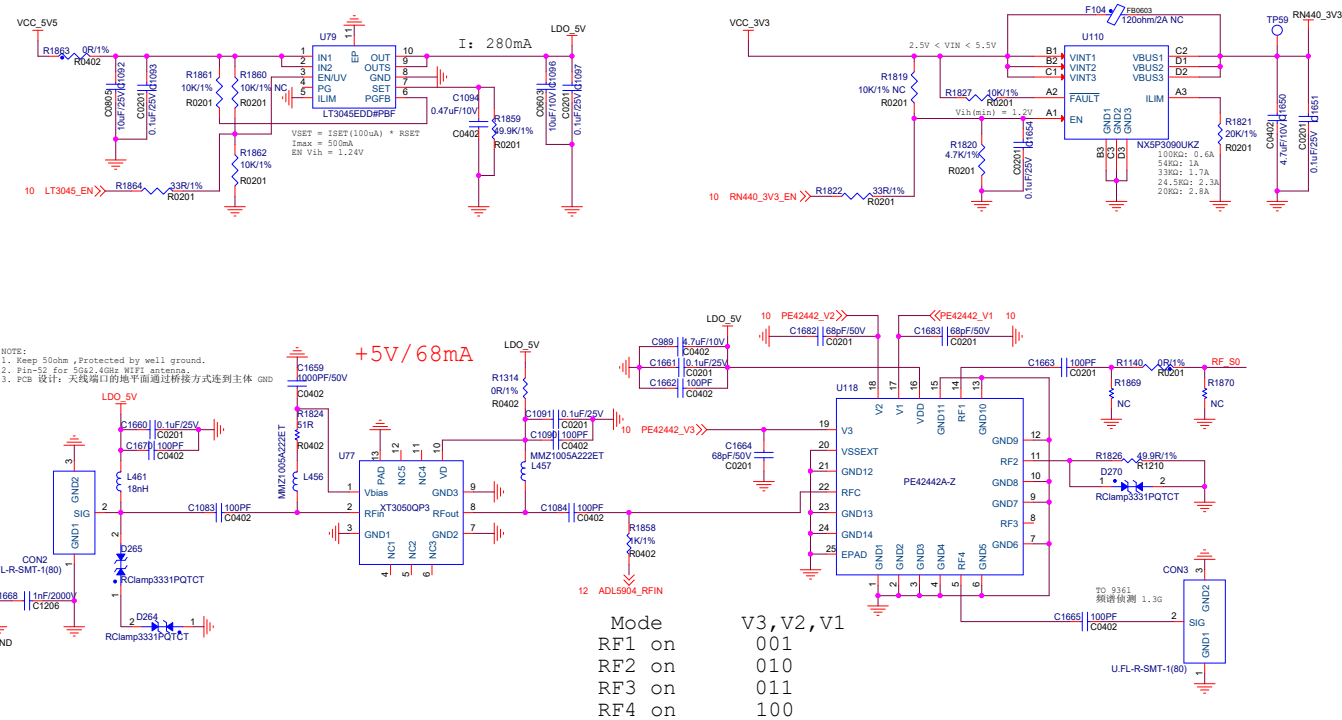
Power input	Current	Power Ripple
VDD_PIO	150mA	Less than 80mV
VDD_3.3V	200~350mA (TYP.) ; 700mA (MAX.)	Less than 80mV

- 2、VDD\_PIO support 1.8V or 3.3V. It mainly depends on the voltage supported by I/O on host side.
- 3、EXT\_LPO (32.768KHz) is Optional, NC if not used.

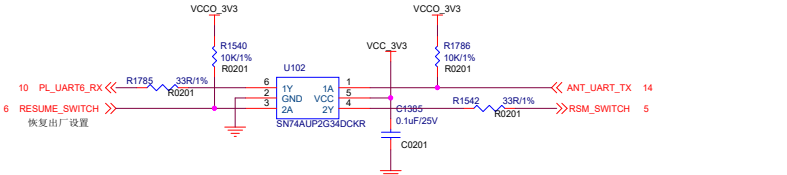
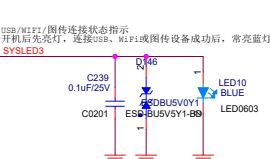
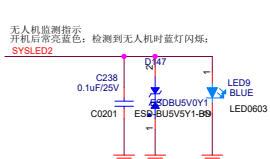
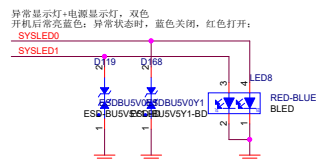
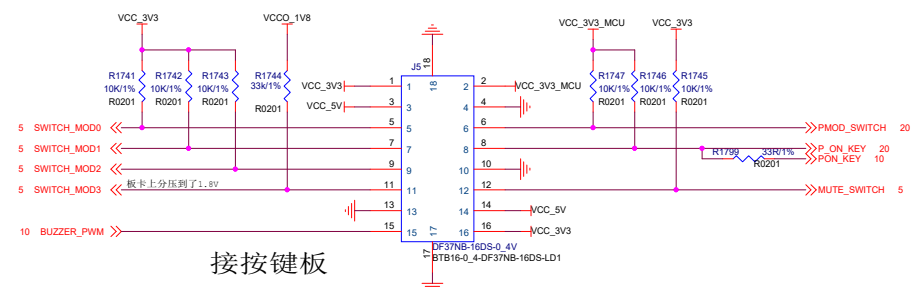
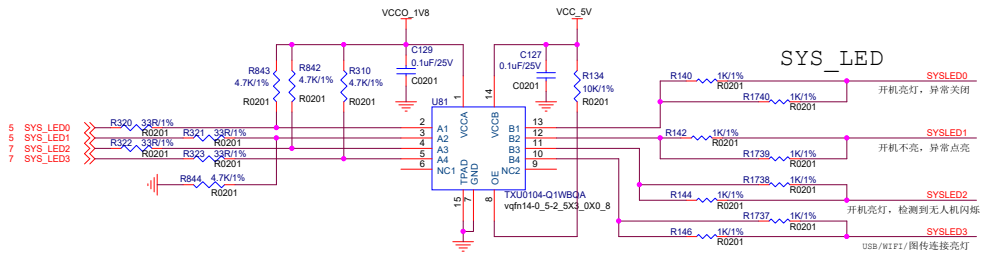




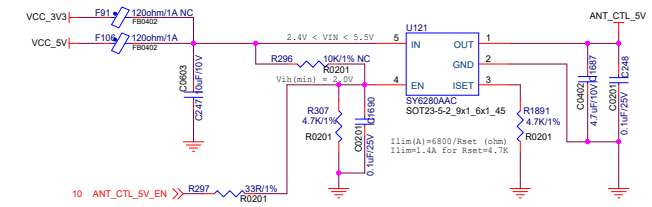
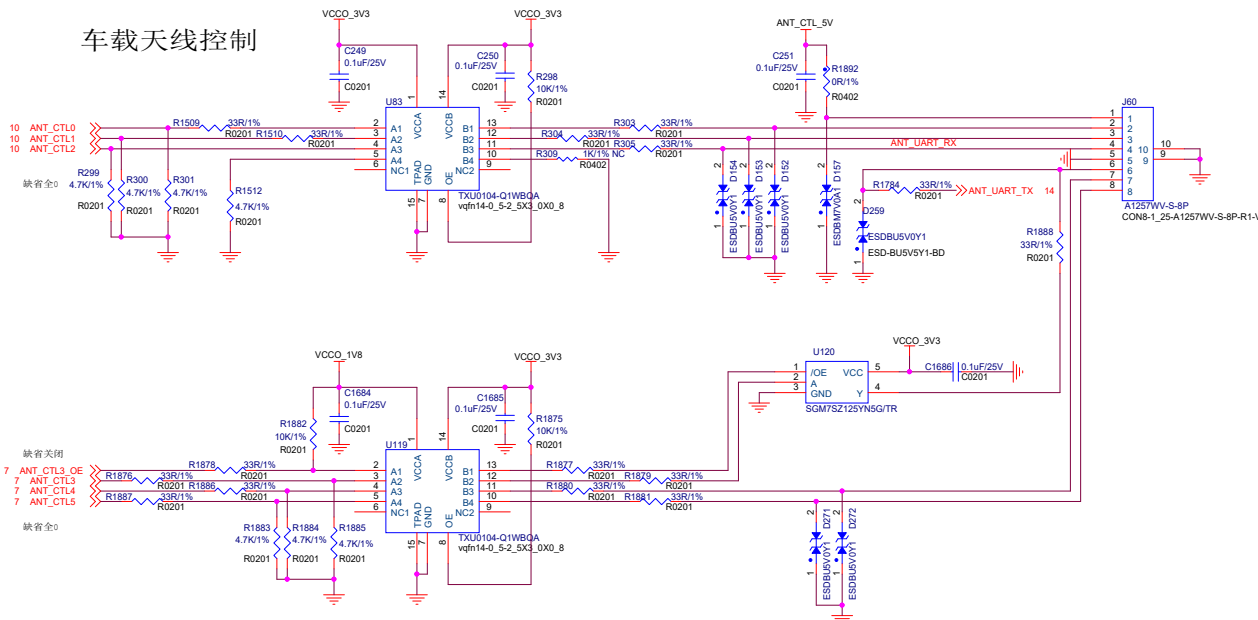
Power input	Current	Power Ripple
VDD_PIO	250mA	Less than 150mV
VDD_3.3V	200-350mA(TYP.), 2.0A(MAX.)	Less than 150mV





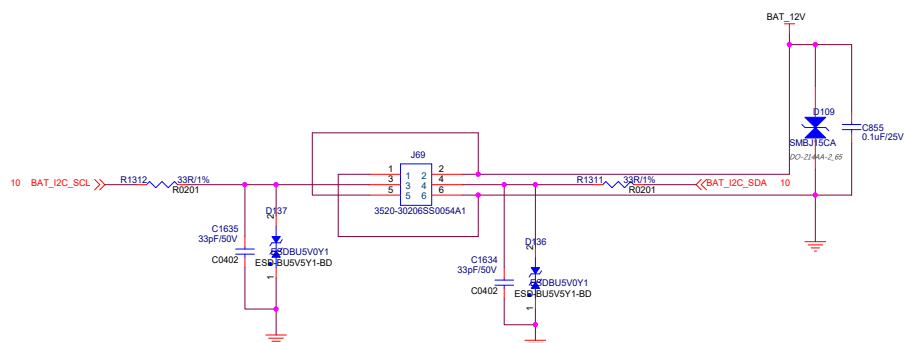


## 车载天线控制



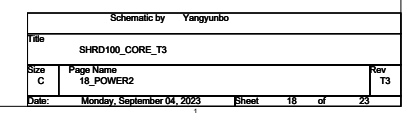
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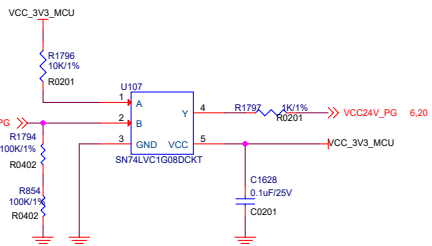
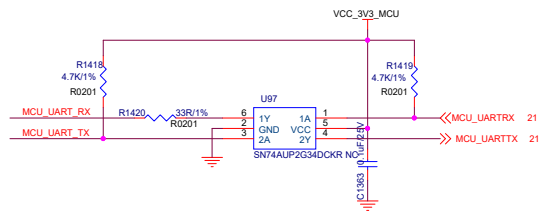
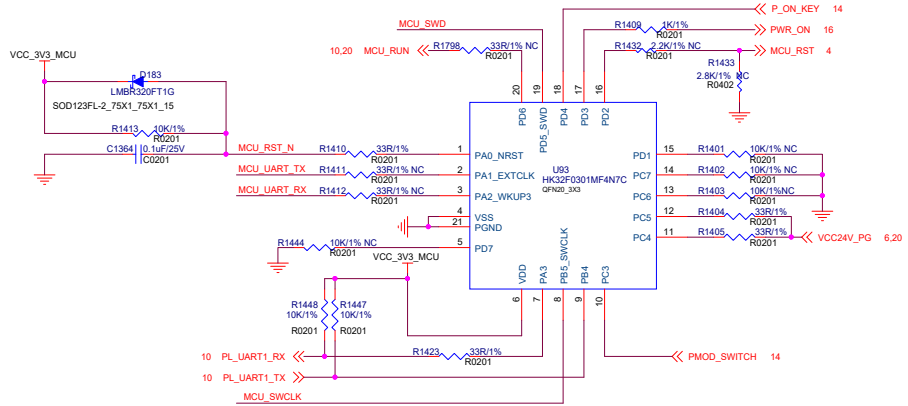
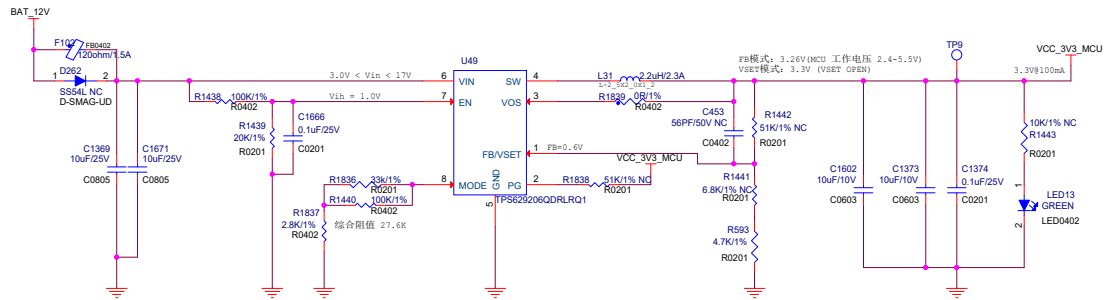
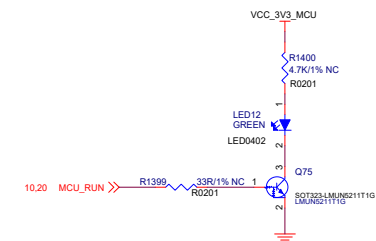
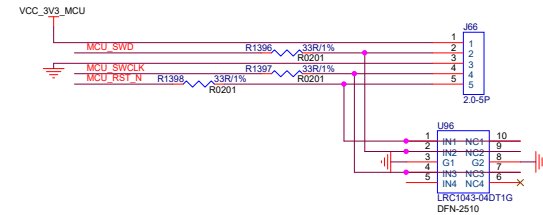


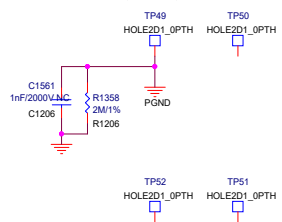
Table 8-1. Smart-CONFIG Setting Table

#	M ODE/S-CONF Level Or Resistor Value [Ω] <sup>(1)</sup>	FB/VSET Pin	F <sub>sw</sub> (MHz)	Output Discharge	Mode (Auto Or Forced PWM)	Dynamic Mode Change
Setting Options by Level						
1	GND	external FB	up to 2.5 <sup>(2)</sup>	yes	Auto PFM/PWM with AEE	Active
2	HIGH (> 1.8 V)	external FB	2.5	yes	Forced PWM	
Setting Options by Resistor						
3	7.50 k	external FB	up to 2.5 <sup>(2)</sup>	no	Auto PFM/PWM with AEE	not active
4	9.31 k	external FB	2.5	no	Forced PWM	
5	11.50 k	external FB	1	yes	Auto PFM/PWM	
6	14.30 k	external FB	1	yes	Forced PWM	
7	17.80 k	external FB	1	no	Auto PFM/PWM	
8	22.10 k	external FB	1	no	Forced PWM	
9	27.40 k	VSET	up to 2.5 <sup>(2)</sup>	yes	Auto PFM/PWM with AEE	
10	34.00 k	VSET	2.5	yes	Forced PWM	
11	42.20 k	VSET	up to 2.5 <sup>(2)</sup>	no	Auto PFM/PWM with AEE	
12	52.30 k	VSET	2.5	no	Forced PWM	
13	64.90 k	VSET	1	yes	Auto PFM/PWM	
14	80.60 k	VSET	1	yes	Forced PWM	
15	100.00 k	VSET	1	no	Auto PFM/PWM	
16	124.00 k	VSET	1	no	Forced PWM	

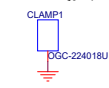




板上的螺钉通孔，  
内直径2.1mm。



SMD 线夹



本版在 SHRD100 CORE T2 基础上，主要修改点如下：  
1、外部天线端口分出 1 路到射频模块，用于频谱侦测；  
2、保留一个螺钉孔接保护地；  
3、增加射频保护电路；  
4、修正 T2 版本的 BUG：DC 电源与BAT电源之间增加防反灌二极管等；

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